These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies are ESD sensitive, ESD precautions shall be observed.

COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01230</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<tbody>
<tr>
<td>Assembly Top</td>
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PLOT NAME = Top Assembly Drawing

GENERATED: 2/8/2017 11:09:51 AM

TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<td>PLOT NAME = Bottom Assembly Drawing</td>
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